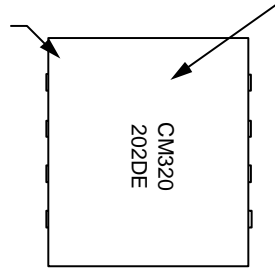


# CM3202-02

## PACKAGE / PINOUT DIAGRAMS

Top View  
(Pins Down View)



# CM3202-02

## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
VIN to GND	[GND – 0.3] to +6.0	V
Pin Voltages VDDQ, VTT to GND ADJSD to GND	[GND – 0.3] to +6.0 [GND – 0.3] to +6.0	V
Output Current VDDQ / VTT, continuous (Note 1) VDDQ / VTT, peak VDDQ Source + VTT Source	2.0 / ±2.0 2.8 / ±2.8 3	A
Temperature Operating Ambient Operating Junction Storage	–40 to +85 –40 to +170 –40 to +150	°C
Thermal Resistance, RJA (Note 2)	55	°C / W
Continuous Power Dissipation (Note 2) WDFN8, TA = 25°C / 85°C	2.6 / 1.5	W
ESD Protection (HBM)	2000	V
Lead Temperature (soldering, 10 sec)	300	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

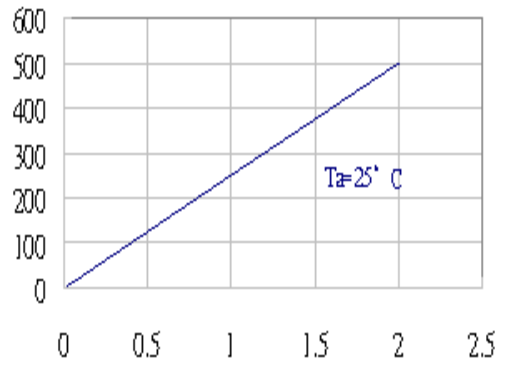
1. Despite the fact that the device is designed to handle large continuous/peak output currents, it is not capable of handling these under all conditions. Limited by the package thermal resistance, the maximum output current of the device cannot exceed the limit imposed by the maximum power dissipation value.
2. Measured with the package using a 4 in<sup>2</sup> / 2 layers PCB with thermal vias.

**Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Ambient Operating Temperature Range	–40 to +85	°C
VDDQ Regulator Supply Voltage, VIN Load Current, Continuous Load Current, Peak (1 sec) CDDQ to GND 3.0 to 3.6 2.8 /	3.0 to 3.6 0 to 2 2.5 220	V A A220 0.3] to +6.0



TYPICAL OPERATING CHARACTERISTICS



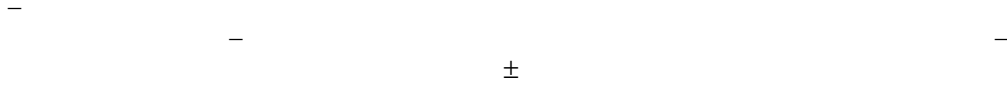
## CM3202-02

### APPLICATION INFORMATION (Cont'd)

$$I_{\text{terminator}} = \frac{0 \text{ mV}}{R(2 \ \Omega)} = 1.2 \text{ mA}$$



#### CM3202-02 Regulator



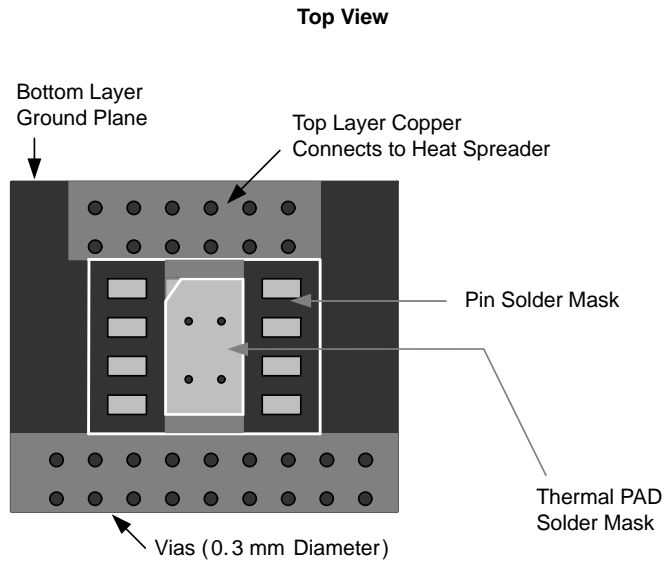


**Adjusting VDDQ Output Voltage**

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APPLICATION INFORMATION (Cont'd)

PCB Layout Considerations

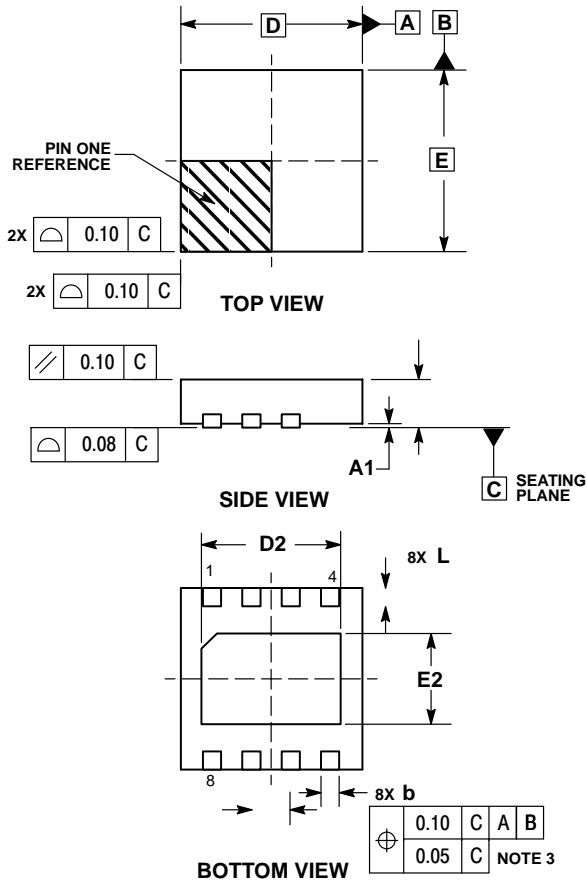


**Figure 2. Thermal Layout for WDFN8 Package**

WDFN8 3x3, 0.65P  
CASE 511BH  
ISSUE O

DATE 21 JUL 2010

SCALE 2:1



NOTES:

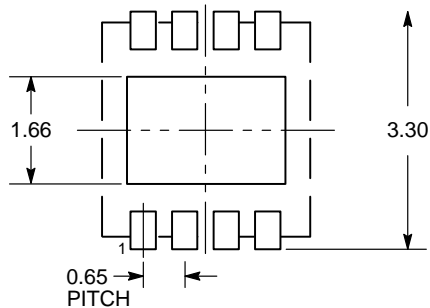
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05

b	0.25	0.35
D	3.00 BSC	
D2	2.20	2.40
E	3.00 BSC	
E2	1.40	1.60
e	0.65 BSC	

L	0.20	0.40
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SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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